

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
100V	28mΩ@10V	50A
	36mΩ@4.5V	

Feature

- Advanced trench technology
- Excellent $R_{DS(on)}$
- Low gate charge

Application

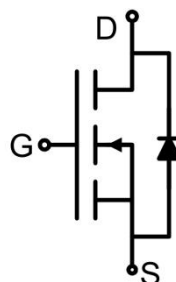
- Automotive lighting
- Load switch
- Uninterruptible power supply

Package

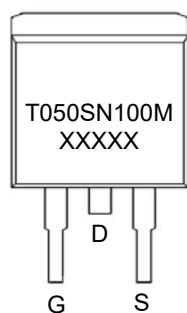


TO-263AB

Circuit diagram



Marking



Absolute Maximum Ratings (T_c=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current (V _{GS} =10V)	I _D	50	A
Continuous Drain Current (V _{GS} =10V, T _C =100°C)	I _D (100°C)	22	A
Pulsed Drain Current ¹⁾	I _{DM}	122	A
Power Dissipation ²⁾	P _D	114	W
Single pulse avalanche energy ³⁾	E _{AS}	59	mJ
Thermal Resistance, Junction-to-Case	R _{θJC}	1.4	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55 ~ +150	°C

Electrical characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250mA	100			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =100V, V _{GS} =0V			1	mA
Gate-body leakage current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250mA	1.2	1.6	2.5	V
Drain-source on-resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A		22	28	mΩ
		V _{GS} =4.5V, I _D =10A		24	36	mΩ
Dynamic characteristics ⁴⁾						
Input Capacitance	C _{iss}	V _{DS} =50V, V _{GS} =0V, f =1MHz		2902		pF
Output Capacitance	C _{oss}			95		
Reverse Transfer Capacitance	C _{rss}			84		
Total Gate Charge	Q _g	V _{DS} =50V, V _{GS} =10V, I _D =20A		72		nC
Gate-Source Charge	Q _{gs}			11		
Gate-Drain Charge	Q _{gd}			19		
Turn-on delay time	t _{d(on)}	V _{DS} =50V, V _{GS} =10V, I _D =20A R _G =3Ω		10		nS
Turn-on rise time	t _r			24		
Turn-off delay time	t _{d(off)}			63		
Turn-off fall time	t _f			45		
Source-Drain Diode characteristics						
Diode Forward Current	I _S				50	A
Diode Forward voltage	V _{SD}	V _{GS} =0V, I _S =30A			1.2	V
Reverse Recovery Time	t _{rr}	I _F =20A, di/dt =100A/μs		29		nS
Reverse Recovery Charge	Q _{rr}			44.4		nC

Notes:

- 1) The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2) The power dissipation is limited by 150°C junction temperature.
- 3) The EAS data shows Max. rating . I_{AS}=15A, V_{DD}=50V, R_G = 25Ω, Starting T_J = 25 °C.
- 4) Guaranteed by design, not subject to production testing.

Typical Characteristics

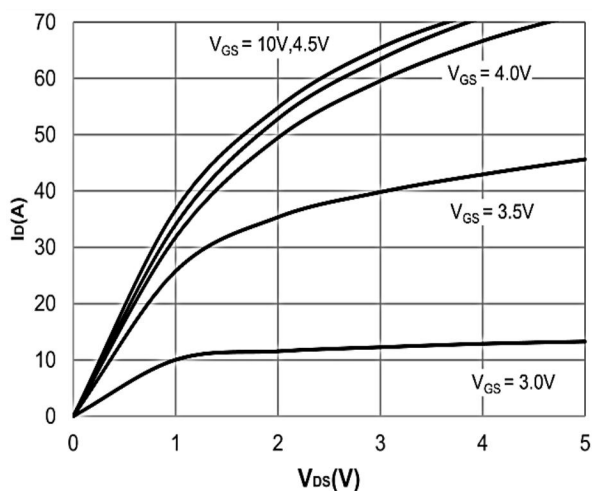


Figure 1: Output Characteristics

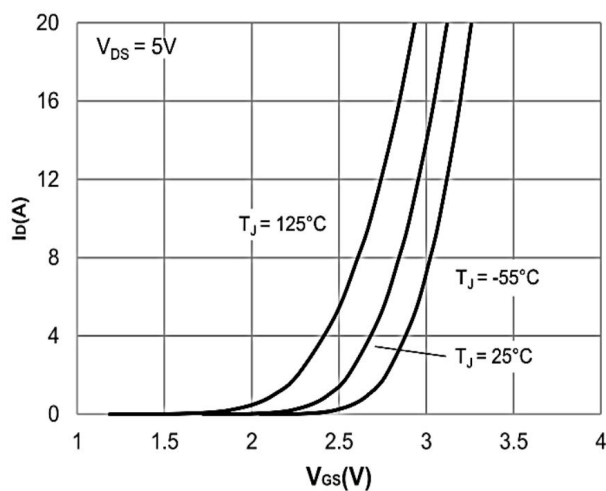


Figure 2: Typical Transfer Characteristics

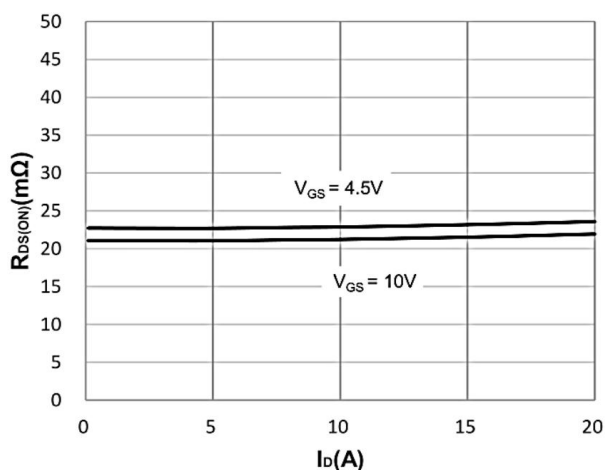


Figure 3: On-resistance vs. Drain Current

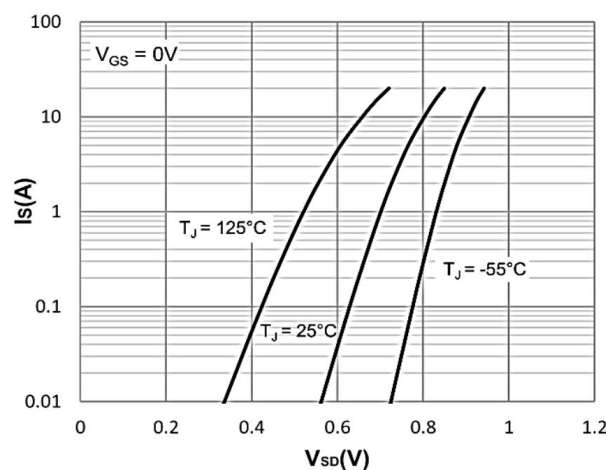


Figure 4: Body Diode Characteristics

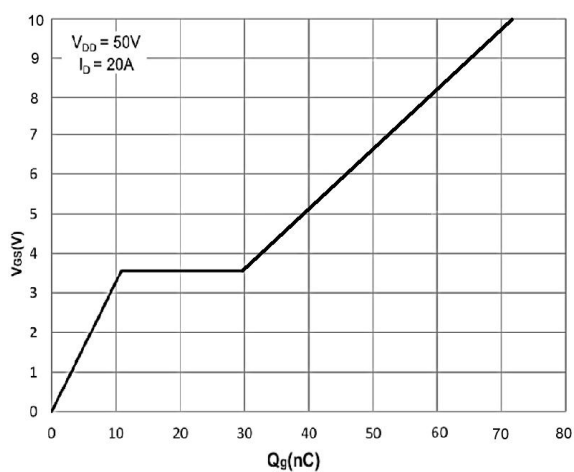


Figure 5: Gate Charge Characteristics

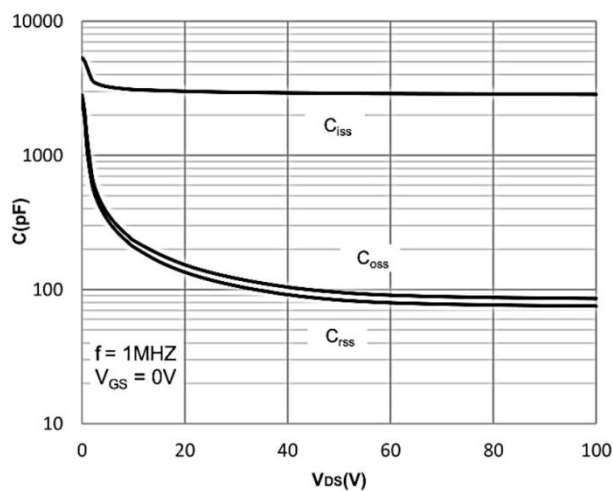


Figure 6: Capacitance Characteristics

Typical Characteristics

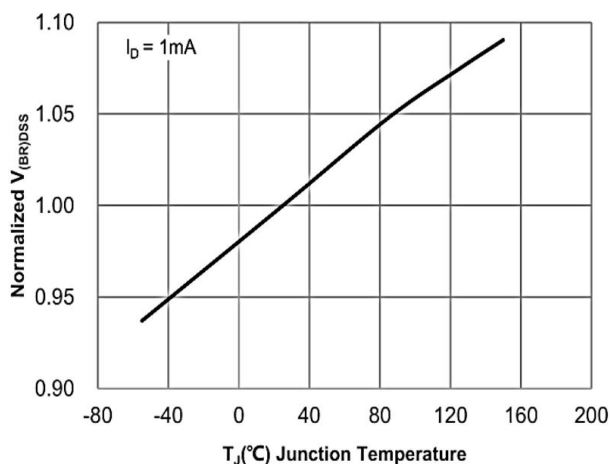


Figure 7: Normalized Breakdown voltage vs. Junction Temperature

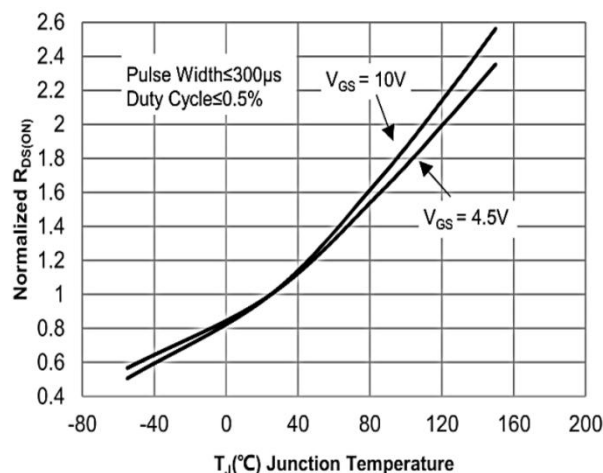


Figure 8: Normalized on Resistance vs. Junction Temperature

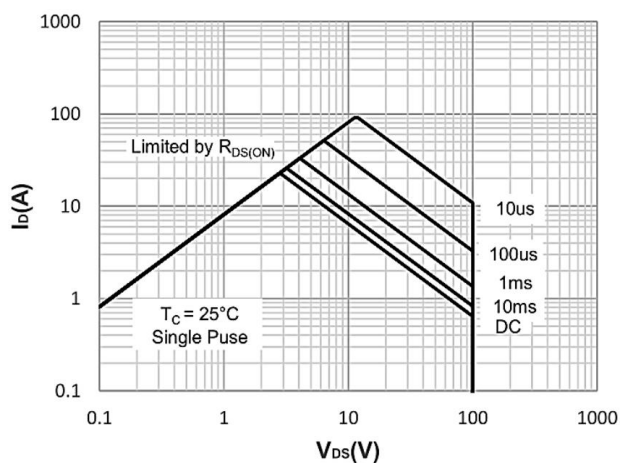


Figure 9: Maximum Safe Operating Area

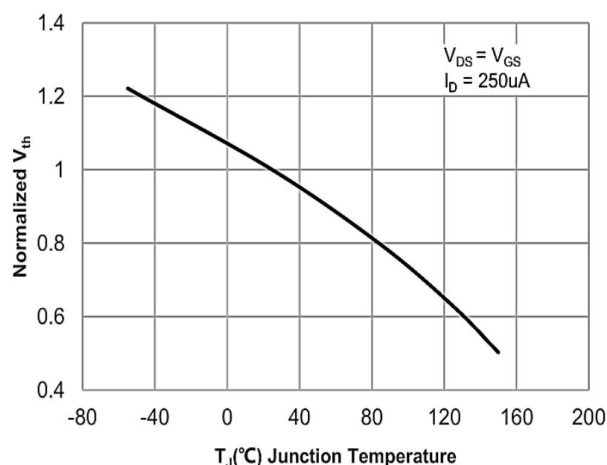


Figure 10: Normalized Threshold Voltage vs. Case Temperature

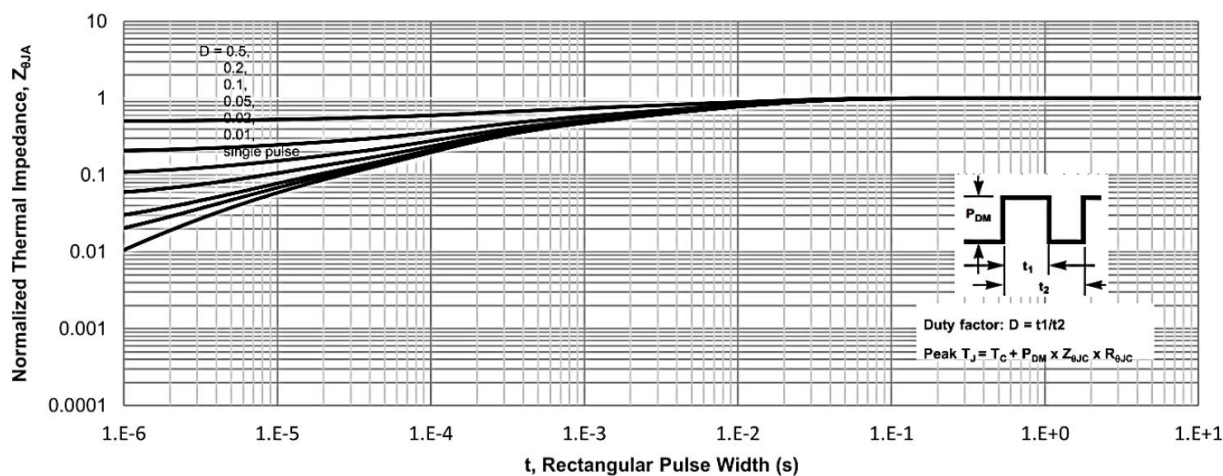
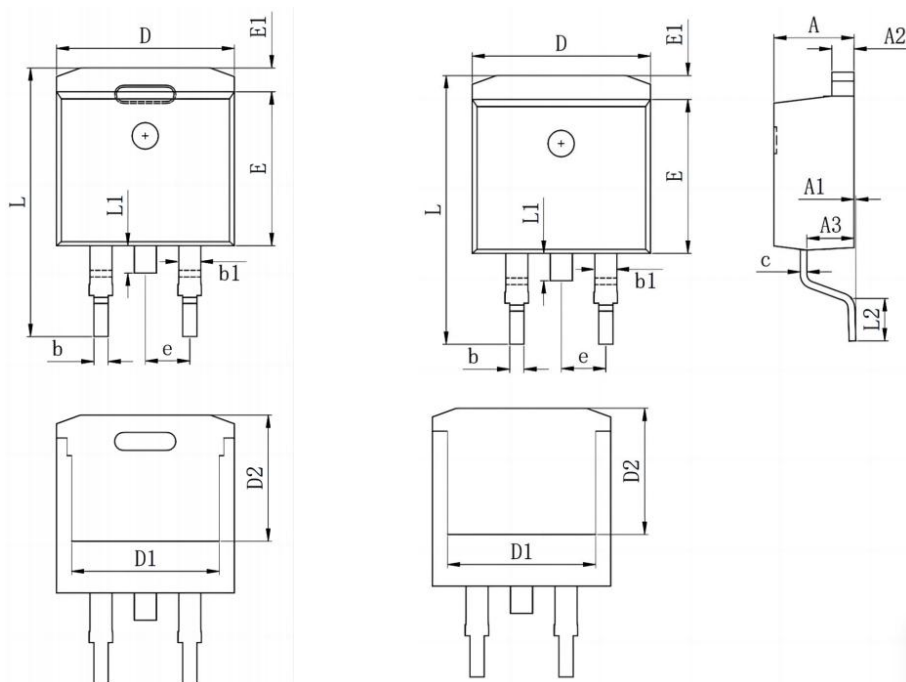


Figure 11: Normalized Maximum Transient Thermal Impedance

TO-263AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.370	4.770	0.172	0.188
A1	0.000	0.250	0.000	0.010
A2	1.220	1.420	0.048	0.056
A3	2.490	2.890	0.098	0.114
b	0.700	0.960	0.028	0.038
b1	1.170	1.470	0.046	0.058
c	0.300	0.530	0.012	0.021
D	9.860	10.360	0.388	0.408
D1	8.400 REF.		0.331 REF.	
D2	7.073 REF.		0.278 REF.	
E	8.500	8.900	0.335	0.350
E1	1.070	1.470	0.042	0.058
e	2.540 BSC.		0.100 BSC.	
L	17.70	15.500	0.697	0.610
L1	1.400	1.700	0.055	0.067
L2	2.000	2.600	0.079	0.102
H	6.000	6.850	0.236	0.270
Q	2.600	3.000	0.102	0.118
φ	3.400	3.800	0.134	0.150